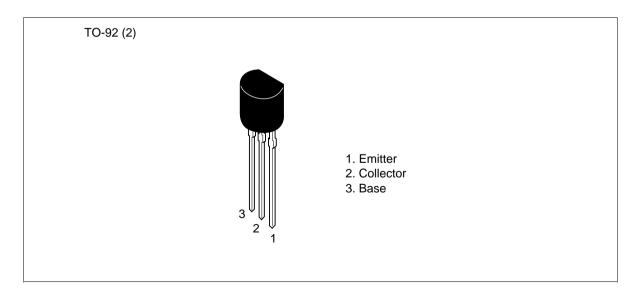
Silicon NPN Epitaxial Planar

HITACHI

Application

- VHF amplifier
- Mixer, Local oscillator

Outline



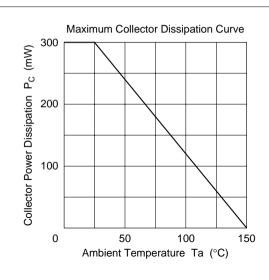


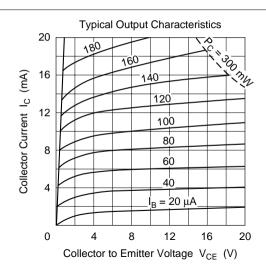
Absolute Maximum Ratings ($Ta = 25^{\circ}C$)

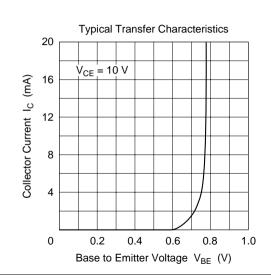
Item	Symbol	Ratings	Unit
Collector to base voltage	V _{CBO}	30	V
Collector to emitter voltage	V _{CEO}	19	V
Emitter to base voltage	V_{EBO}	2	V
Collector current	I _c	50	mA
Emitter current	I _E	– 50	mA
Collector power dissipation	P _c	300	mW
Junction temperature	Tj	150	°C
Storage temperature	Tstg	-55 to +150	°C

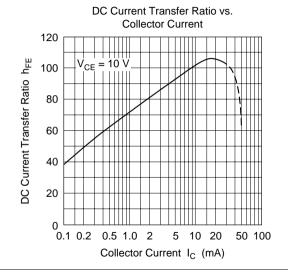
Electrical Characteristics ($Ta = 25^{\circ}C$)

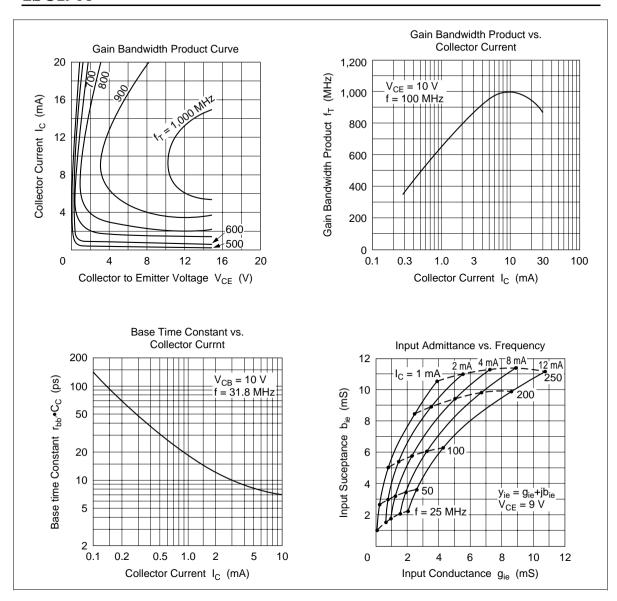
Item	Symbol	Min	Тур	Max	Unit	Test conditions
Collector to base breakdown voltage	$V_{(BR)CBO}$	30	_	_	V	$I_{c} = 10 \ \mu A, \ I_{E} = 0$
Collector to emitter breakdown voltage	$V_{(BR)CEO}$	19	_	_	V	$I_{\rm C}$ = 3 mA, $R_{\rm BE}$ = ∞
Emitter to base breakdown voltage	$V_{(BR)EBO}$	2	_	_	V	$I_{E} = 10 \ \mu A, \ I_{C} = 0$
Collector cutoff current	I _{CBO}	_	_	0.5	μΑ	V _{CB} = 10 V, I _E = 0
DC current transfer ratio	h _{FE}	40	_	_		$V_{CE} = 10 \text{ V}, I_{C} = 10 \text{ mA}$
Gain bandwidth product	f _T	600	1000	_	MHz	$V_{CE} = 10 \text{ V}, I_{C} = 10 \text{ mA}$
Collector output capacitance	Cob	_	1.0	2.0	pF	$V_{CB} = 10 \text{ V}, I_{E} = 0, f = 1 \text{ MHz}$
Collector to emitter saturation voltage	$V_{\text{CE(sat)}}$	_	0.2	1.0	V	$I_{\rm C}$ = 20 mA, $I_{\rm B}$ = 4 mA
Base time constant	r _{bb′} ⋅C _C	_	10	25	ps	$V_{CB} = 10 \text{ V}, I_{C} = 10 \text{ mA},$ f = 31.8 MHz
Power gain	PG	_	33	_	dB	$V_{CE} = 10 \text{ V}, \qquad f = 45 \text{ MHz}$ $I_C = 5 \text{ mA}$
		_	18	_	dB	$V_{CE} = 10 \text{ V}, \qquad f = 200 \text{ MHz}$ $I_{C} = 5 \text{ mA}$

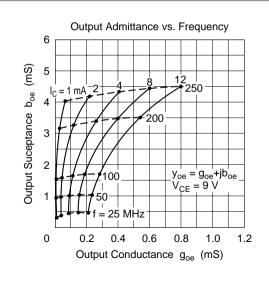


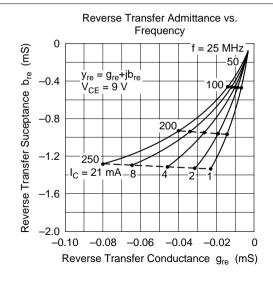


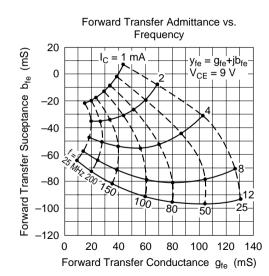


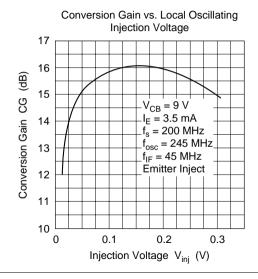


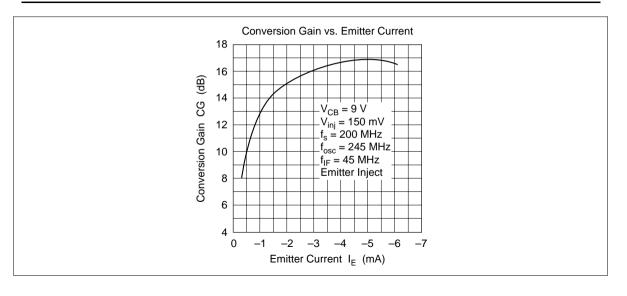




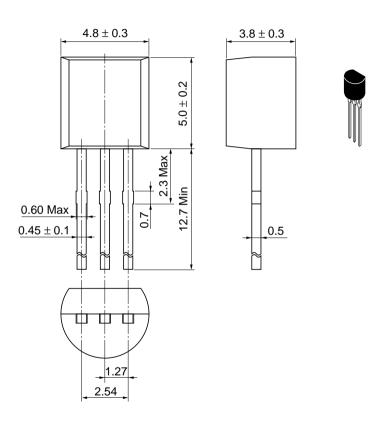








Unit: mm



Hitachi Code	TO-92 (2)
JEDEC	Conforms
EIAJ	Conforms
Weight (reference value)	0.25 g

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